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This listing of claims will replace all prior versions, and listings, of claims in the application:

LISTING OF CLAIMS:

Claim 1 (previously presented): An integrated electronic component comprising:
a ceramic substrate including circuit elements and external electrodes disposed on side surfaces of the ceramic substrate; and
a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate; wherein
bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a tapered shape having obtuse angles with respect to the bottom edges of the substrate-facing segments; and
the external electrodes are not disposed in the corners of the top surface of the ceramic substrate.

Claim 2 (previously presented): An integrated electronic component according to Claim 1, wherein the metal case includes side segments, the substrate-facing segments are seamlessly connected to the side segments at positions opposing the corners of the top surface of the ceramic substrate, and the substrate-facing segments are separated from the top segment, thereby the substrate-facing segments being supported at borders with the side segments in a cantilevered fashion.

Claim 3 (original): An integrated electronic component according to Claim 1, wherein the circuit elements are disposed within the ceramic substrate.

Claim 4 (original): An integrated electronic component according to Claim 1, wherein the circuit elements are mounted on the ceramic substrate.

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Claim 5 (original): An integrated electronic component according to Claim 1, wherein the metal case is of at least one of phosphor bronze and nickel silver.

Claim 6 (original): An integrated electronic component according to Claim 1, wherein the ceramic substrate includes a plurality of laminated ceramic sheets.

Claim 7 (original): An integrated electronic component according to Claim 1, wherein the metal case has a substantially box-like shape.

Claim 8 (original): An integrated electronic component according to Claim 1, wherein the obtuse angles are within the range of $145^{\circ} \leq \theta \leq 170^{\circ}$.

Claim 9 (original): An integrated electronic component according to Claim 1, wherein each of the notches has a length in a first direction that is within the range of about 0.25 mm to about 0.30 mm and a length in a second direction that is within the range of about 0.05 mm to about 0.15 mm.

Claim 10 (original): An integrated electronic component according to Claim 1, wherein the ceramic substrate has a length of about 5.0 mm to about 6.5 mm, and has a width of about 4.0 mm to about 4.5 mm.

Claim 11 (previously presented): An integrated electronic component comprising:

a ceramic substrate including circuit elements and external electrodes disposed on side surfaces of the ceramic substrate; and

a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate; wherein

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bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a substantially circular arc shape; and

the external electrodes are not disposed in the corners of the top surface of the ceramic substrate.

Claim 12 (previously presented): An integrated electronic component according to Claim 11, wherein the metal case includes side segments, the substrate-facing segments are seamlessly connected to the side segments at positions opposing the corners of the top surface of the ceramic substrate, and the substrate-facing segments are separated from the top segment, thereby the substrate-facing segments being supported at borders with the side segments in a cantilevered fashion.

Claim 13 (original): An integrated electronic component according to Claim 11, wherein the circuit elements are disposed within the ceramic substrate.

Claim 14 (original): An integrated electronic component according to Claim 11, wherein the circuit elements are mounted on the ceramic substrate.

Claim 15 (original): An integrated electronic component according to Claim 11, wherein the metal case is of at least one of phosphor bronze and nickel silver.

Claim 16 (original): An integrated electronic component according to Claim 11, wherein the ceramic substrate includes a plurality of laminated ceramic sheets.

Claim 17 (original): An integrated electronic component according to Claim 11, wherein the metal case has a substantially box-like shape.

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Claim 18 (original): An integrated electronic component according to Claim 11, wherein a radius of curvature R of the notches is about 0.05 mm to about 0.2 mm.

Claim 19 (original): An integrated electronic component according to Claim 11, wherein the ceramic substrate has a length of about 5.0 mm to about 6.5 mm, and has a width of about 4.0 mm to about 4.5 mm.

Claim 20 (previously presented): An integrated electronic component comprising:

a ceramic substrate including circuit elements; and

a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate; wherein

bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a tapered shape having obtuse angles with respect to the bottom edges of the substrate-facing segments; and

a portion of a top edge of each of the substrate-facing segments is spaced from a bottom surface of the top segment.

Claim 21 (previously presented): An integrated electronic component comprising:

a ceramic substrate including circuit elements; and

a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate; wherein

bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a substantially circular arc shape; and

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a portion of a top edge of each of the substrate-facing segments is spaced from a bottom surface of the top segment.

Claim 22 (previously presented): An integrated electronic component comprising:

a ceramic substrate including circuit elements; and

a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate; wherein

bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a tapered shape having obtuse angles with respect to the bottom edges of the substrate-facing segments; and

the metal case includes side segments, the substrate-facing segments are seamlessly connected to the side segments at positions opposing the corners of the top surface of the ceramic substrate, such that the substrate-facing segments are supported at borders with the side segments in a cantilevered fashion.

Claim 23 (previously presented): An integrated electronic component comprising:

a ceramic substrate including circuit elements; and

a metal case having a top segment and substrate-facing segments and being mounted on the ceramic substrate; wherein

bottom edges of the substrate-facing segments oppose a top surface of the ceramic substrate, the substrate-facing segments have notches at positions opposing corners of the top surface of the ceramic substrate, and the notches have a substantially circular arc shape; and

the metal case includes side segments, the substrate-facing segments are seamlessly connected to the side segments at positions opposing the corners of the top

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surface of the ceramic substrate, such that the substrate-facing segments are supported at borders with the side segments in a cantilevered fashion.